

## FEATURES

- | Excellent capability of absorbing transient surge
- | Quick response to surge voltage
- | Eliminates over voltage caused by fast rising transients
- | Solid-state silicon technology, non degenerative



SMA(DO-214AC)



Marking



Schematic Symbol

## APPLICATIONS

- | Audio/Video line
- | Network and telecom
- | Data lines and security systems
- | Serial ports

## APPROVALS

<b>RoHS</b>	Compliance with 2011/65/EU
<b>HF</b>	Compliance with IEC61249-2-21:2003

## ELECTRICAL CHARACTERISTICS

Part Number	$V_{DRM}$	$V_S$	$V_T$	$I_{DRM}$	$I_S$	$I_T$	$I_H$	$C_o$
	Min. (V)	Max. (V)	Max. (V)	Max. ( $\mu$ A)	mA	Max. (A)	Min. (mA)	Typ.(pF)
STA45B90	90.0	130.0	4.0	5.0	800.0	2.2	120.0	45.0

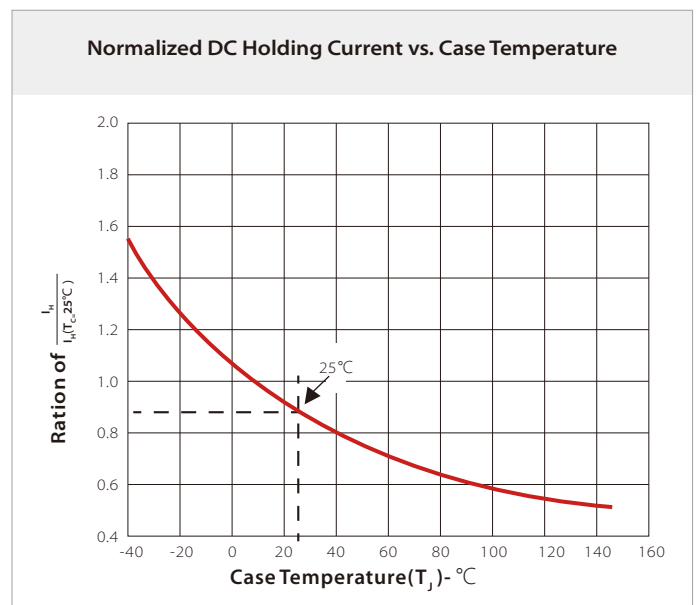
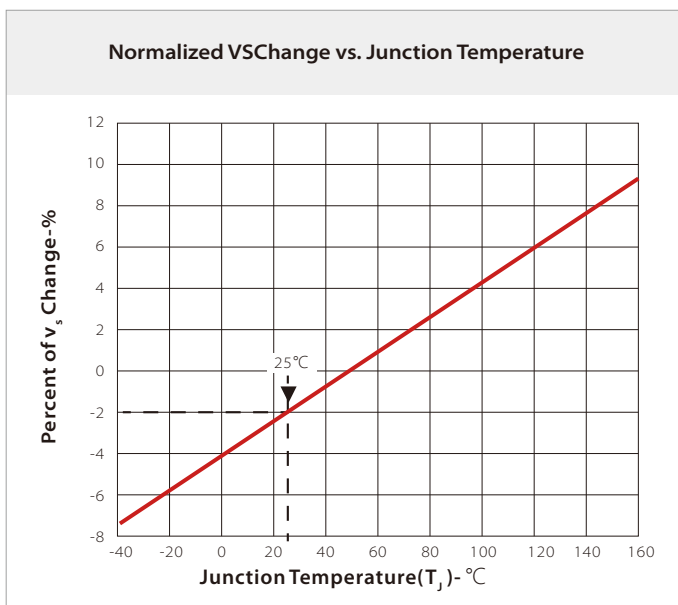
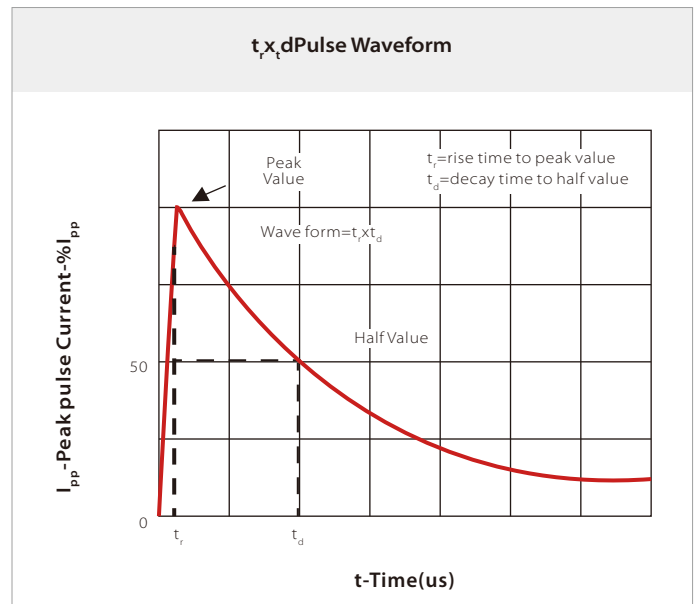
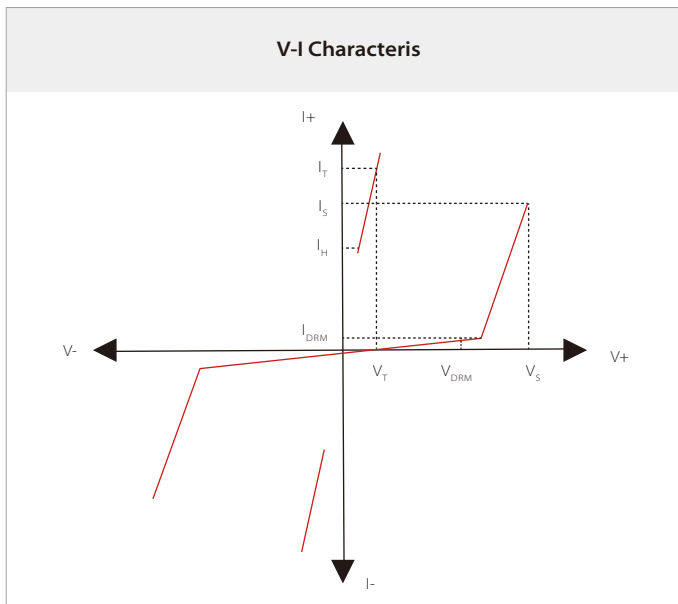
## SURGE RATINGS

Part Number	$I_{PP}$ 2x10us	$I_{PP}$ 8x20us	$I_{PP}$ 10x560us	$I_{PP}$ 10x1000us	$V_{PP}$ 10x700us	$I_{TSM}$ 60Hz	$d_t/d_t$
	(A)	(A)	(A)	(A)	(V)	(A)	(A/us)
STA45B90	150	150	50	45	3000	20	500

## THERMAL CONSIDERATIONS

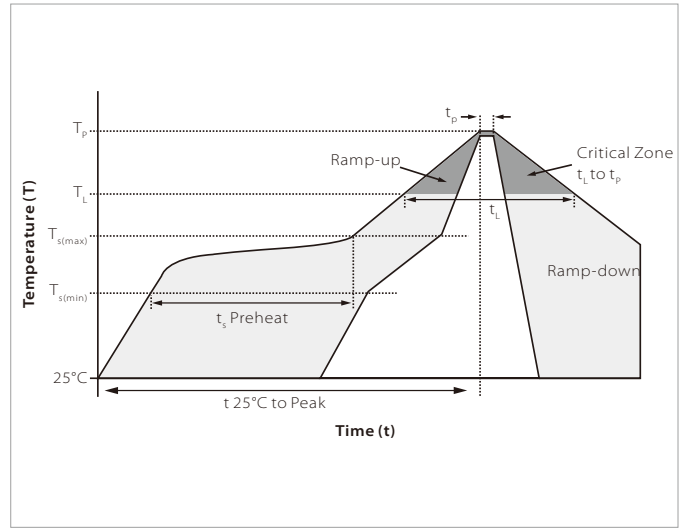
Symbol	Parameter	Value	Unit
$R_{\theta JA}$	Junction to Ambient on printed circuit	120	C/W
$T_J$	Operating Junction Temperature	-55 to +150	C
$T_{STG}$	Storage Temperature Range	-55 to +150	C

## RATINGS AND CHARACTERISTIC CURVES ( $T_A = 25^\circ\text{C}$ )

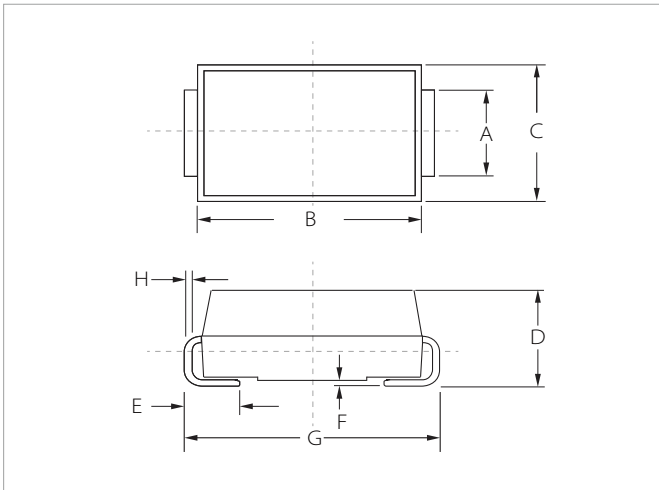


## SOLDERING PARAMETERS

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Max ( $T_{s(min)}$ )	150°C
	Temperature Max ( $T_{s(max)}$ )	200°C
	Time (min to max) ( $t_p$ )	60 – 180 secs
Average ramp up rate (Liquidus Temp ( $T_L$ ) to peak		3°C/second max
$T_{s(max)}$ to $T_L$ - Ramp-up Rate		3°C/second max
Reflow	Temperature ( $T_L$ ) (Liquidus)	217°C
	Time (min to max) ( $t_r$ )	60 – 150 seconds
Peak Temperature ( $T_p$ )		260°C
Time within 5°C of actual peak Temperature ( $t_p$ )		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature ( $T_p$ )		8 minutes max.
Do not exceed		260°C

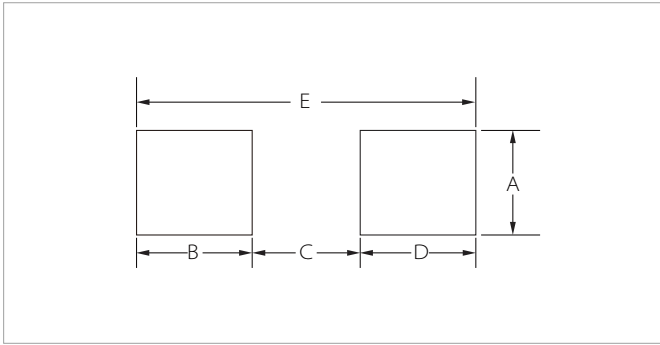


## DO-214AC(SMA) PACKAGE INFORMATION



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	1.20	1.60	0.047	0.063
B	4.20	4.60	0.165	0.181
C	2.60	2.80	0.102	0.110
D	2.10	2.40	0.083	0.094
E	0.76	1.52	0.030	0.060
F	0.02	0.20	0.001	0.008
G	4.85	5.25	0.191	0.207
H	0.15	0.30	0.006	0.012

## RECOMMENDED PAD LAYOUT DIMENSIONS



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	1.63	-	0.064	-
B	1.45	-	0.057	-
C	-	2.80	-	0.090
D	1.45	-	0.057	-
E	5.28REF		0.208REF	

## ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
STA45B90	DO-214AC(SMA)	5000PCS	13"

**Headquarters**

No.3387 Shendu Road Pujiang  
I&E Park  
Minhang Shanghai China  
201000

**Hotline**

400-021-5756

**Web**

<https://www.semiware.com>

**Sales Center**

Tel: 86-21-3463-7458  
Email: [sales18@semiware.com](mailto:sales18@semiware.com)

**Customer Service**

Tel: 86-21-5484-1001  
Email: [sales17@semiware.com](mailto:sales17@semiware.com)

**Technical Support**

Tel: 86-21-3463-7654  
Email: [fae01@semiware.com](mailto:fae01@semiware.com)

**Complaint & Suggestions**

Tel: 86-21-3463-7172  
Ext: 8868  
Email: [cs03@semiware.com](mailto:cs03@semiware.com)

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Website



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